



N-Channel SiC Power MOSFET

TO-247-3L (*Prefix :W)

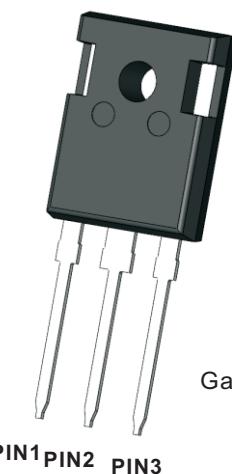
V_{Ds}	1200V
I_D@25°C	30A
R_{Ds(on)}	80 mΩ

DESCRIPTION

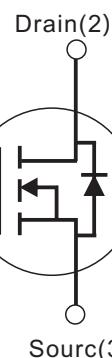
- 3rd Generation Sic Mosfet Technology
- High Blocking Voltage With Low On-resistance
- High-speed Switching With Low Capacitances
- Halogen Free, RoHS Compliant.

Features

- Reduce switching losses and minimize gate ringing
- Higher system efficiency
- Reduce cooling requirements
- Increase power density
- Increase system switching frequency



RoHS
COMPLIANT



SYMBOL

ABSOLUTE MAXIMUM RATINGS (TA=25°C, unless otherwise specified)

PARAMETER	Symbols	RATINGS	Test Conditions	Units
Drain-Source Voltage	V _{DSS}	1200	VGS=0V, ID=100μA	V
Gate-Source Voltage	V _{GSMAX}	-8/+22	Absolute maximum values	V
Gate-Source Voltage	V _{GSOOP}	-5/+18	Recommended operational values	V
Continuous Drain Current	I _D	30	VGS=18V, Tc=25°C	A
Continuous Drain Current	I _D	20	VGS=18V, Tc=100°C	A
Pulsed Drain Current (Note 1)	I _{D(Pulse)}	80	Pulse width tp limited by Tjmax	A
Power Dissipation	P _D	250	Tc=25°C	W
Operating junction and storage temperature	T _j , T _{stg}	-55 ~ +175		°C

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Thermal Resistance

PARAMETER	Symbols	RATINGS	Units
Thermal resistance, junction – case.	R _{thJC}	0.6	°C/W
Thermal resistance, junction – ambient(min. footprint)	R _{thJA}	40	°C/W



ELECTRICAL CHARACTERISTICS (TA=25°C, unless otherwise specified)

PARAMETER	Symbols	TEST CONDITIONS	Min	Typ	Max	Units
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=100\mu A$	1200			V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=1200V, V_{GS}=0V$			100	μA
		$V_{DS}=1200V, V_{GS}=0V, T_j=175^\circ C$			500	
Gate- Source Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=18V$			200	nA
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=5mA$	2.0	3.2	4.0	V
Static Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=18V, I_D=20A, T_j=25^\circ C$		80	96	$m\Omega$
		$V_{GS}=18V, I_D=20A, T_j=175^\circ C$		120		
DYNAMIC CHARACTERISTICS						
Input Capacitance	C_{iss}	$V_{GS}=0V, V_{DS}=1000V$ $f=1MHz$ $V_{AC}=25mV$		1100		pF
Output Capacitance	C_{oss}			56		pF
Reverse Transfer Capacitance	C_{rss}			15		pF
Gate resistance	R_G	$f=1MHz, V_{AC}=25mV$		2.1		Ω
Transconductance $T_c=25^\circ C$	g_{fs}	$V_{DS}=20V, I_D=33A$		11		S
Turn-On Energy (Body Diode)	E_{ON}	$V_{DS}=800V, V_{GS}=-5/18V,$ $I_D=20A, L=80\mu H$		450		μJ
Turn-Off Energy (Body Diode)	E_{OFF}			110		μJ
Total Gate Charge (Note 1)	Q_G	$V_{DS}=800V$ $V_{GS}=-5V/18V$ $I_D=20A$		75		nC
Gate-Source Charge	Q_{GS}			21		nC
Gate-Drain Charge	Q_{GD}			14		nC
Turn-On Delay Time (Note 1)	$t_{D(ON)}$	$V_{DS}=800V, V_{GS}=-5/18V,$ $I_D=20A, R_G=0 \Omega$ Timing relative to V_{DS}		28		ns
Turn-On Rise Time	t_R			65		ns
Turn-Off Delay Time	$t_{D(OFF)}$			24		ns
Turn-Off Fall Time	t_F			20		ns
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
Maximum Body-Diode Continuous Current	I_S	$T_j=25^\circ C$			30	A
Drain-Source Diode Forward Voltage (Note 1)	V_{SD}	$I_{SD}=10A, V_{GS}=-5V$		3.5		V
Reverse Recovery Time (Note 1)	t_{rr}	$I_F=20A, V_{GS}=-5V, di/dt$ $=1200A/us, VR=800V$		16		ns
Reverse Recovery Charge	Q_{rr}			75		μC

Notes:

1. Pulse Test: Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$.



Typical Characteristics

Fig.1 Typical forward Output characteristics at $T_j=25^\circ\text{C}$

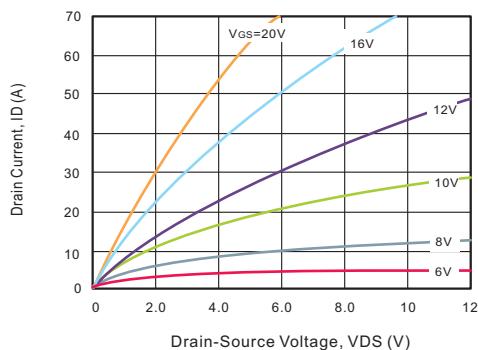


Fig.2 Typical forward Output characteristics at $T_j=175^\circ\text{C}$

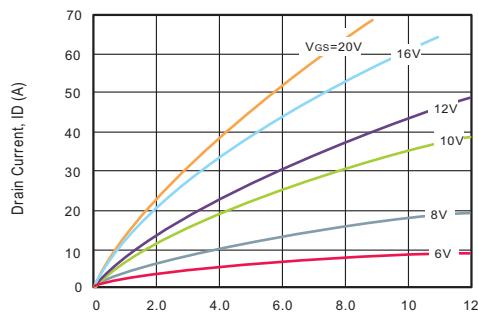


Fig.3 On-Resistance vs. Gate Voltage for various Temperature

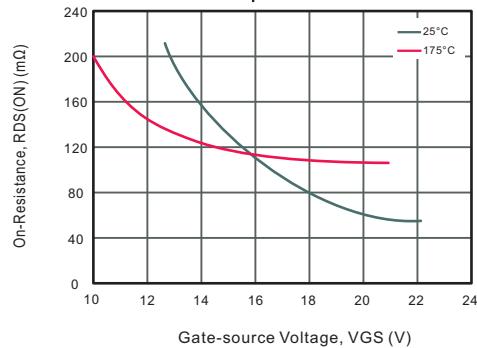


Fig.4 Threshold Voltage vs. Temperature

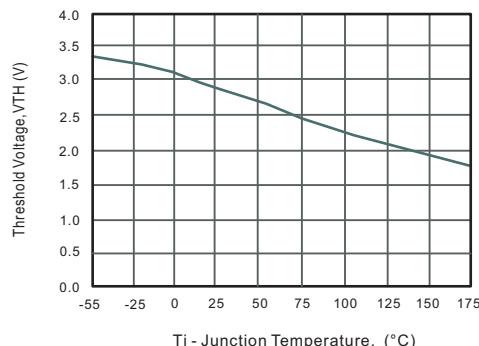


Fig.5 On-Resistance vs. Junction Temperature

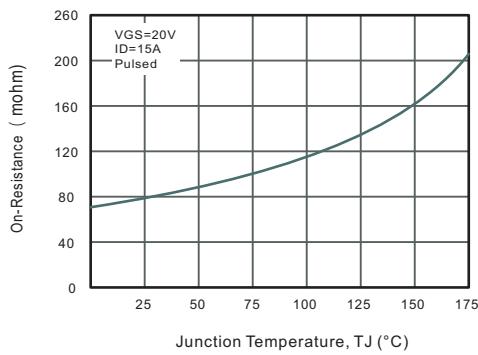


Fig.6 Diode Forward Voltage vs. Current

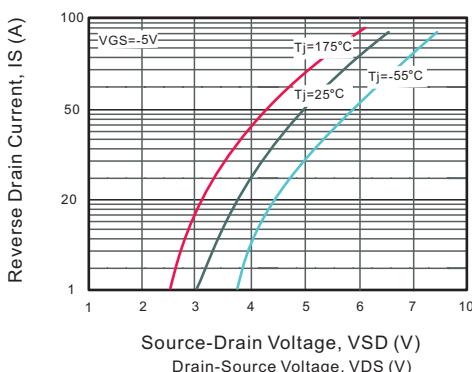


Fig.7 Capacitance Characteristics

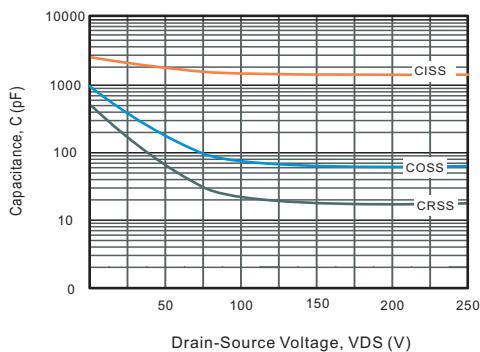
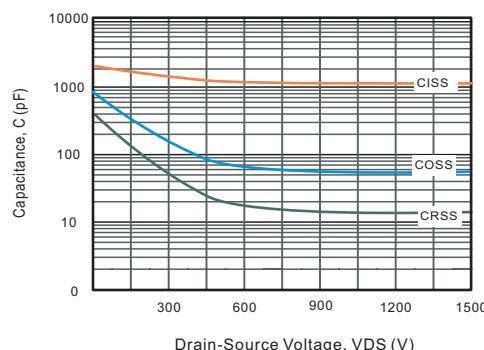


Fig.8 Capacitance Characteristics





Typical Characteristics

Fig.9 Safe Operating Area

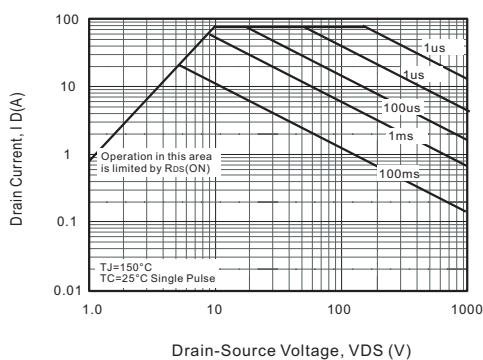


Fig.10 Drain Current Derating

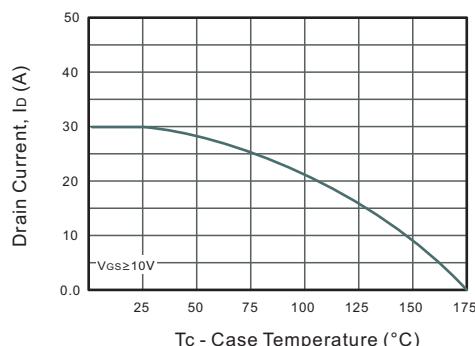


Fig.11 Gate Charge Characteristics

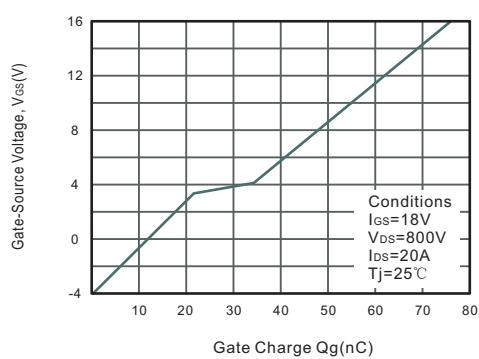


Fig.12 Power Dissipation

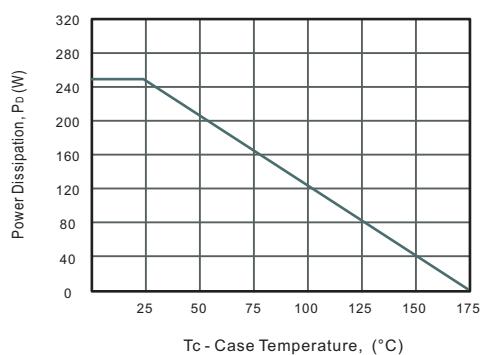
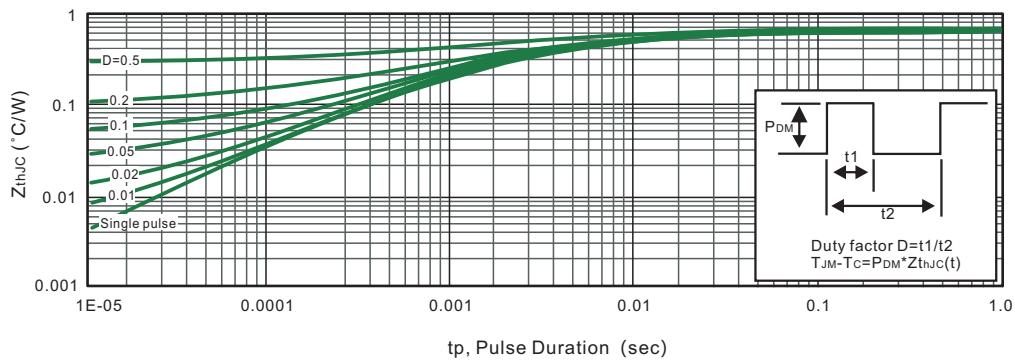


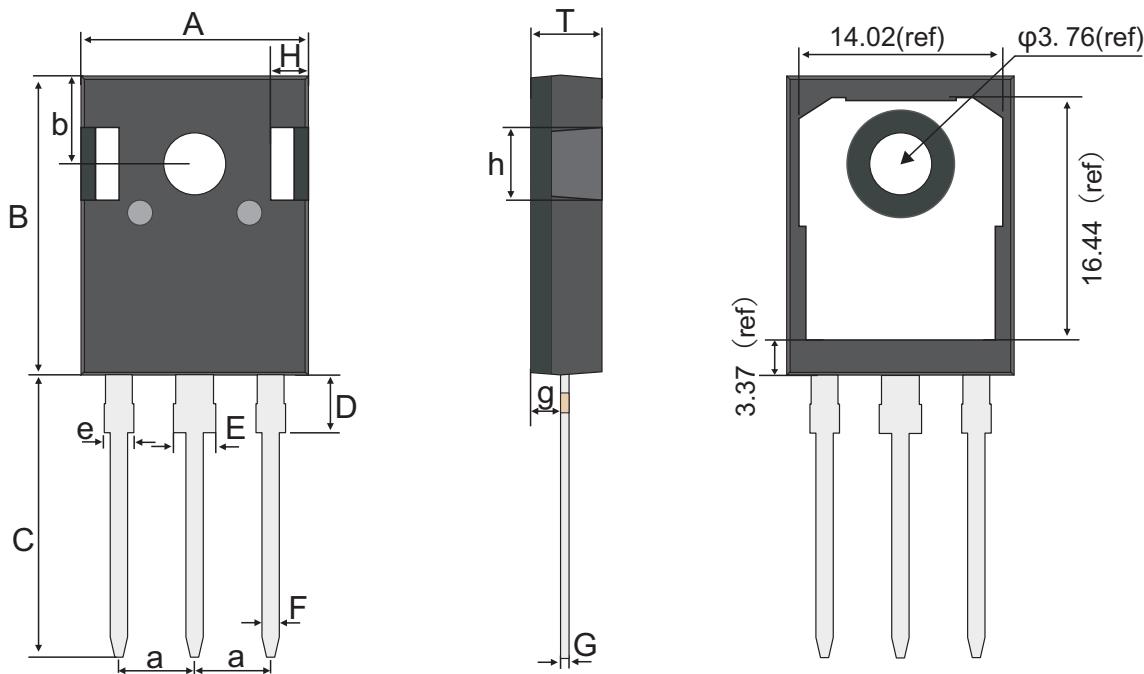
Fig.13 Max. Transient Thermal Impedance





Package Outline
Through Hole Package ; 3 leads

TO-247-3L



TO-247-3L mechanical data

UNIT		A	a	B	b	C	D	E	e	F	G	g	H	h	T
mm	max	16.01	5.54	21.18	6.26	20.2	4.25	3.25	2.2	1.3	0.7	2.49	2.71	5.37	5.2
	typ	15.81	5.44	20.98	6.16	20.0	4.15	3.10	2.05	1.2	0.6	2.39	2.51	5.17	5.0
	min	15.61	5.34	20.78	6.06	19.8	4.05	2.95	1.9	1.1	0.5	2.29	2.31	4.97	4.8
mil	max	630	218	834	246	795	167	128	87	51	28	98	107	211	205
	typ	622	214	826	243	787	163	122	81	47	24	94	99	204	197
	min	615	210	818	239	780	159	116	75	43	20	90	91	196	189

Marking

Type number	Marking code
SC080N120WH	SC080N120WH



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